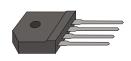
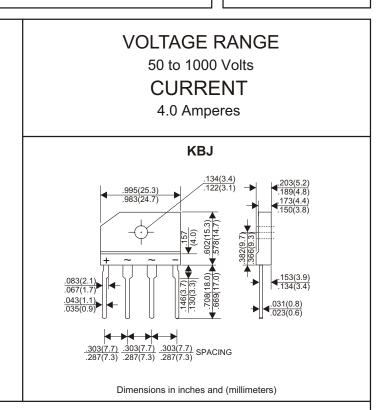
KBJ401 THRU **KBJ407**

SINGLE PHASE 4.0 AMP BRIDGE RECTIFIERS



FEATURES

- * Ideal for printed circuit board
- * Low forward voltage
- * Low leakage current
- * Mounting position: Any



GW

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwies specified. Single phase half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

	KBJ401	KBJ402	KBJ403	KBJ404	KBJ405	KBJ406	KBJ407	UNITS
е	50	100	200	400	600	800	1000	V
	35	70	140	280	420	560	700	V
	50	100	200	400	600	800	1000	V
k Note 1)	4.0							
atsink)	2.4							A
e half sine-wave								
nod)	150						Α	
e Element at 2.0A D.C.	1.0						V	
Ta=25°C	5.0						Α	
Ta=100°C	500						A	
	5.5						°C/W	
	6.0						°C/W	
	-55—+150						°C	
	-55 +150						°C	
	Ta=100°C	ge 50 35 50 nk Note 1) 50 atsink) 10 le half sine-wave 10 hod) 10 ge Element at 2.0A D.C. 10 Ta=25°C 100°C 0 10	je 50 100 35 70 50 100 ak Note 1) 100 atsink) 100 le half sine-wave 100 hod) 100 ge Element at 2.0A D.C. 100 Ta=25°C 100°C	je 50 100 200 35 70 140 50 100 200 nk Note 1) 100 200 atsink) - - le half sine-wave - - nod) - - ge Element at 2.0A D.C. - - Ta=25°C - - - - -	je 50 100 200 400 35 70 140 280 50 100 200 400 hk Note 1) 4.0 4.0 atsink) 2.4 2.4 le half sine-wave 150 150 nod) 150 5.0 Ta=25°C 5.0 5.0 Ta=100°C 500 6.0 -55-+15 -55-+15	je 50 100 200 400 600 35 70 140 280 420 50 100 200 400 600 nk Note 1) 4.0 4.0 atsink) 2.4 le half sine-wave 150 100 150 ge Element at 2.0A D.C. 1.0 1.0 Ta=25°C 5.0 5.0 Ta=100°C 500 6.0 -55 - +150 -55 - +150	je 50 100 200 400 600 800 35 70 140 280 420 560 50 100 200 400 600 800 nk Note 1) 4.0 4.0 600 800 atsink) 2.4 4.0 2.4 150 le half sine-wave 150 100 150 100 ge Element at 2.0A D.C. 1.0 1.0 1.0 1.0 Ta=25°C 5.0 5.0 5.0 5.5 5.5 6.0 -5.5 6.0 -55-+150 5.5 5.5	35 70 140 280 420 560 700 50 100 200 400 600 800 1000 hk Note 1) 4.0 4.0 4.0 300 1000 atsink) 2.4 2.4 5.0 100 le half sine-wave 150 100 150 ge Element at 2.0A D.C. 1.0 1.0 Ta=25°C 5.0 5.0 Ta=100°C 500 5.5 6.0 -55 - +150

NOTES

1. Device mounted on 50mm x 50mm x 1.6mm Cu Plate Heatsink.

2. Thermal Resistance from Junction to Case with device mounted on 50mm x 50mm x 1.6mm Cu Plate Heatsink.

3. Thermal Resistance from Junction to Lead without Heatsink.

